

# 曜凌光電股份有限公司

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### **RX240128A-YHW**

### **SPECIFICATION**

### **CUSTOMER:**

APPROVED BY	
PCB VERSION	
DATE	

FOR CUSTOMER USE ONLY

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

Release DATE:



# **Revision History**

VERSION	DATE	REVISED PAGE NO.	Note
0	2012/04/28		First issue
Α	2013/04/19		Modify Supply
			Current 120 MAX
			Modify Display
			Command
			Correct VLCD
			Correct pin
			Description.
В	2014/11/26		Remove IC
			information



### Contents

- 1.General Specification
- 2. Module Classification Information
- 3.Interface Pin Function
- 4. Contour Drawing
- 5. Optical Characteristics
- 6. Absolute Maximum Ratings
- 7. Electrical Characteristics
- 8.Backlight Information
- 9.Reliability
- 10.Inspection specification
- 11.Precautions in use of LCD Modules
- 12. Material List of Components for RoHs
- 13.Recommendable Storage



## 1.General Specification

The Features is described as follow:

■ Module dimension: 98.7 x 67.7 x 9.5 mm

■ View area: 92.0 x 53.0 mm

Active area: 83.975 x 44.775 mm

■ Number of dots: 240 x 128

■ Dot size: 0.325 x0.325 mm

■ Dot pitch: 0.35 x 0.35 mm

■ LCD type: STN Positive, Yellow Green Transflective

■ Duty: 1/128

■ View direction: 6 o'clock

■ Backlight Type: LED White

■ IC: UC1608



### 2. Module Classification Information

R	<u>X</u>	240128	<u>A</u>	_	<u>Y</u>	<u>H</u>	W
①	2	3	4	_	(5)	6	7

Item	Description							
1	R : Raystar O	ptronics Inc.						
2	Display	C: Character Type,		T:TAB Type				
		G: Graphic Type		X:COG Type				
3		240 * 128 dot						
4	Serials code :							
		P→TN Positive, Gray		V→FSTN Ne	egative, Blue			
		N→TN Negative,		T→FSTN Ne	egative, Black			
		L→VA Negative			egative (Double film)			
	_	H→ HTN Positive, Gray		F→FSTN Po				
5	LCD	I→HTN Negative, Black		K→FSC Neg				
		U→HTN Negative, Blue		S→FSC Pos				
		B→STN Negative, Blue			gative, Black			
		G→STN Positive, Gray	-	C→CSTN Negative, Black				
		Y→STN Positive, Yellow	Green	A→ASTN Negative, Black				
	Polarizer	A: Reflective, N.T, 6:00		K: Transflective, W.T,12:00				
	Type,	D: Reflective, N.T, 12:0	700	1 : Transflective, U.T,6:00				
	турс,	G: Reflective, W. T, 6:00		4 : Transflective, U.T.12:00				
6	Temperature	J: Reflective, W. T, 12:0		C: Transmissive, N.T,6:00				
0	range,	0 : Reflective, U. T, 6:00		F: Transmissive, N.T,12:00				
	\	3 : Reflective, U. T, 12:0		I : Transmissive, W. T, 6:00 L : Transmissive, W.T,12:00				
	View direction	B: Transflective, N.T,6:0 E: Transflective, N.T.12						
	direction	H: Transflective, W.T,6:		2: Transmissive, U. T, 6:00 5: Transmissive, U.T,12:00				
		N→ Without backlight	W→LE[		H→LED, High light White			
	. 1	P→EL, Blue	A→LED		S→LED, Full color			
		T→EL, Green	R→LED	•	J→DIP LED, Blue			
_		D→EL, White		), Orange	K→DIP LED, White			
7	Backlight	M→EL, Yellow Green	B→LED	<u> </u>	E→DIP LED, Yellow			
		F→CCFL, White		, Dual color	L→DIP LED, Amber			
		Y→LED, Yellow Green		, Full color	I→DIP LED, Red			
		G→LED, Green		·				



# 3.Interface Pin Function

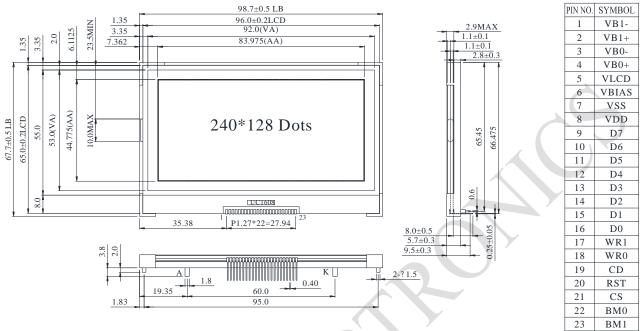
Pin No.	Symbol	Type	Description						
1	VB1-		LCD Bias Voltages. These are the voltage source to						
2	VB1+		provide SEG driving currents. These voltages are generated internally. Connect capacitors of CBX between						
3	VB0-	PWR	VBX+ and VBX–.						
4	VB0+		The resistance of these four traces directly affects the SEG driving strength of the resulting LCD module. Minimize the trace resistance is critical in achieving high quality image.						
5	VLCD	PWR	Main LCD Power Supply. Connect these pins together.						
6	VBIAS	I	This is the reference voltage to generate the actual SEG driving voltage. VBIAS can be used to fine tune VLCD by external variable resistors. Internal resistor network has been provided to simplify external trimming circuit.  In COF application, connect a small bypass capacitor between VBIAS and VSS to reduce noise.						
7	VSS	PWR	Ground						
8	VDD	PWR	Supply Voltage for logic						
9	D7		Bi-directional bus for both serial and parallel host						
10	D6		interfaces. In serial modes, connect D[0] to SCK, D[3] to SDA,						
11	D5		BM=1x BM=0x BM=01 BM=00						
12	D4		(Parallel) (Parallel) (S9) (S8/S8uc)   D0   D0/D4   SCK   SCK						
13	D3	I/O	D1 D1 D1/D5 D2/D6						
14	D2		D3 D3 D3/D7 SDA SDA						
15	D1		D5 D5						
16	D0		D6						
17	WR1		WR[1:0] controls the read/write operation of the host interface. See Host Interface section for more detail.  In parallel mode, WR[1:0] meaning depends on whether						
18	WR0	l	the interface is in the 6800 mode or the 8080 mode. In serial interface modes, these two pins are not used, connect them to VSS.						



			Select Control data or Display data for read/write							
19	CD	I	operation. In S9 mode, CD pin is not used. Connect CD to							
			VSS when not used. "L": Control data "H": Display data							
			When RS	T="L", all	control registers are re-initialized by					
			their defa	ult states						
20	RST	I	Since UC	1608x ha	s built-in Power-ON-Reset and Software					
			Reset cor	mmand. F	RST pin is not required for proper chip					
					ST is not used, connect the pin to VDD.					
			operation	. VVIICII IV	to 1 is not used, connect the pin to VDD.					
21	CS		Chip Sele	ct. The c	hip is selected when CS="H". When the					
21	00	'	chip is not selected, D[7:0] will be high impedance.							
			Bus mode	e: The inte	erface bus mode is determined by					
			BM[1:0] a	nd D[7:6]	by the following relationship:					
22	BM0		BM[1:0]	D[7:6]	Mode					
			11	Data	6800/8-bit					
			10	Data	8080/8-bit					
			01	0X	6800/4-bit					
		-	00	0X	8080/4-bit					
								01	10	3-wire SPI w/ 9-bit token (S9: conventional)
23	BM1		00	10	4-wire SPI w/ 8-bit token					
DIVIT					(S8: conventional)					
			00	11	3- or 4-wire SPI w/ 8-bit token					
					(S8uc: Ultra-Compact)					



# 4.Contour Drawing



The non-specified tolerance of dimension is  $\pm 0.2$ mm.



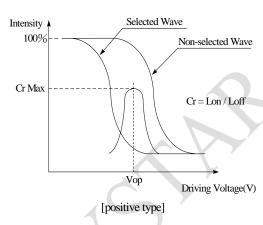


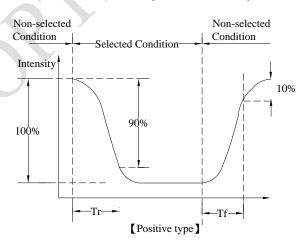
## **5.Optical Characteristics**

Item	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR≧2	0	_	20	ψ= 180°
Viou Anglo	θ	CR≧2	0	_	40	ψ= 0°
View Angle	θ	CR≧2	0	_	30	ψ= 90°
	θ	CR≧2	0		30	ψ= 270°
Contrast Ratio	CR	_	_	3		_
Doonongo Timo	T rise	_	_	200	300	ms
Response Time	T fall	_	A.	250	350	ms

#### **Definition of Operation Voltage (Vop)**

#### **Definition of Response Time (Tr, Tf)**



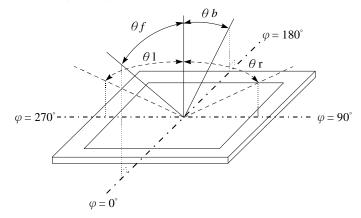


#### **Conditions:**

Operating Voltage : Vop Viewing Angle( $\theta$ ,  $\phi$ ) :  $0^{\circ}$ ,  $0^{\circ}$ 

Frame Frequency: 64 HZ Driving Waveform: 1/N duty, 1/a bias

### **Definition of viewing angle(CR≥2)**





# **6.Absolute Maximum Ratings**

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	T <sub>OP</sub>	-20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	T <sub>ST</sub>	-30	_	+80	$^{\circ}$
Logic supply voltage	$V_{DD}$	-0.3	_	+4.0	V
LCD Generator supply voltage	V <sub>DD</sub> 2	-0.3	_	+4.0	V
LCD Generated voltage	V <sub>LCD</sub>	-0.3	^	+17.0	V



### 7. Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	$V_{DD}$ - $V_{SS}$		2.7	2.8~3.3	3.6	V
		Ta=-20°C	_	_	_	V
Supply Voltage For LCM	$V_{LCD}$	Ta=25°C	15.2	15.5	15.8	V
		Ta=70°C	_	- ,		V
Input High Volt.	V <sub>IH</sub>	_	0.8 V <sub>DD</sub>	7	7)	V
Input Low Volt.	V <sub>IL</sub>	_	_		0.2 V <sub>DD</sub>	V
Output High Volt.	V <sub>OH</sub>	_	0.8 V <sub>DD</sub>		_	V
Output Low Volt.	V <sub>OL</sub>	- (	(-)	_	0.2 V <sub>DD</sub>	V
Supply Current(No		N	7			
include	$I_{DD}$	V <sub>DD</sub> =3.0V	_	1.1	_	mA
LED Backlight)						

Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance.



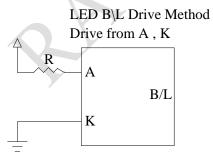
# 8.Backlight Information

### **Specification**

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	86.4	96	120	mA	V=3.5V
Supply Voltage	V	3.3	3.5	3.7	V	4
Reverse Voltage	VR	_	_	5	V	-
Luminance	IV	400	500	_	CD/M2	ILED=96mA
(Without LCD)	IV	400	300		ODINE	ILLD-John A
Wave Length	Х	0.28	0.3	0.32		ILED=96mA
wave Length	Y	0.28	0.3	0.32	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	ILLD-90IIIA
LED Life Time				X		ILED≦96mA
(For Reference	_	_	50K	)-	Hr.	25℃,50-60%RH,
only)						(Note 1)
Color	White					

Note: The LED of B/L is drive by current only; driving voltage is only for reference To make driving current in safety area (waste current between minimum and maximum).

Note 1:50K hours is only an estimate for reference.





# 9.Reliability

Content of Reliability Test (Wide temperature, -20°C~70°C)

Environmental Test							
Test Item	Content of Test	Test Condition	Note				
High Temperature storage	Endurance test applying the high storage temperature for a long time.	200hrs	2				
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30℃ 200hrs	1,2				
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70℃ 200hrs					
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20℃ 200hrs	1				
High Temperature/ Humidity storage	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60℃,90%RH 96hrs	1,2				
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation  -20°C 25°C 70°C  30min 5min 30min 1 cycle	-20℃/70℃ 10 cycles					
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3				
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5kΩ CS=100pF 1 time					

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.



# 10.Inspection specification

NO	Item	Criterion			AQL	
01	Electrical Testing	defect. 1.2 Missing character, dot 1.3 Display malfunction. 1.4 No function or no display		olay. exceeds product specifications.		0.65
02	Black or white spots on LCD (display only)	2.1 White and black spots three white or black spo		on display $\leq$ 0.25mm, no more than obs present.  Here than two spots or lines within 3mm		2.5
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type: $\Phi = (x + y) / 2$ $X \longrightarrow X$ 3.2 Line type: (A)	2 1 7 Y	SIZE $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$	Acceptable Q TY Accept no dense  2 1 0 Acceptable Q TY Acceptable Q TY Accept no dense  2 As round type	2.5
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.		Size Φ $Φ \le 0.20$ $0.20 < Φ \le 0.50$ $0.50 < Φ \le 1.00$ $1.00 < Φ$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5



NO	Item	Criterion			AQL
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination			
			Glass thickness a: LCD	thickness I side length	
		6.1 General glass chip	:		$\supset$
		O. T. T Chip on parier sur	face and crack between	paners.	
		z: Chip thickness	y: Chip width	x: Chip length	
06	Chipped	Z≦1/2t	Not over viewing area	x≦1/8a	2.5
	glass	1/2t <z≦2t< td=""><td>Not exceed 1/3k</td><td>x≦1/8a</td><td></td></z≦2t<>	Not exceed 1/3k	x≦1/8a	
		⊙ If there are 2 or more 6.1.2 Corner crack:	chips, x is total length of	of each chip.	
		z: Chip thickness	y: Chip width	x: Chip length	
		Z≦1/2t	Not over viewing area	x≦1/8a	
		1/2t < z ≦ 2t	Not exceed 1/3k	x≦1/8a	
		⊙ If there are 2 or more	chips, x is the total leng	yth of each chip.	



NO	Item	Criterion			
		Symbols:			
		x: Chip length y: Chip width z: Chip thickness			
		k: Seal width t: Glass thickness a: LCD side length			
		L: Electrode pad length			
		6.2 Protrusion over terminal :			
		6.2.1 Chip on electrode pad :			
		Z Z	7		
		y: Chip width x: Chip length z: Chip thickness			
		$y \le 0.5 \text{mm} \qquad x \le 1/8 \text{a} \qquad 0 < z \le t$			
		6.2.2 Non-conductive portion:			
06	Glass crack	y 12 X X	2.5		
		y: Chip width x: Chip length z: Chip thickness			
		y≦ L			
		⊙If the chipped area touches the ITO terminal, over 2/3 of the ITO			
		must remain and be inspected according to electrode terminal specifications.			
		<ul> <li>⊙ If the product will be heat sealed by the customer, the alignment</li> </ul>			
		mark not be damaged.			
		6.2.3 Substrate protuberance and internal crack.			
	7	x			
		y: width x: length			
		$y \le 1/3L$ $x \le a$			



NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	<ul><li>8.1 Illumination source flickers when lit.</li><li>8.2 Spots or scratched that appear when lit must be judged.</li><li>Using LCD spot, lines and contamination standards.</li></ul>	0.65 2.5
		8.3 Backlight doesn't light or color wrong.	0.65
09	Bezel	<ul><li>9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.</li><li>9.2 Bezel must comply with job specifications.</li></ul>	
		<ul><li>10.1 COB seal may not have pinholes larger than 0.2mm or contamination.</li><li>10.2 COB seal surface may not have pinholes through to the IC.</li></ul>	2.5
		10.3 The height of the COB should not exceed the height indicated in the assembly diagram.	2.5 0.65
		10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places.	2.5
10	PCB · COB	<ul> <li>10.5 No oxidation or contamination PCB terminals.</li> <li>10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.</li> </ul>	2.5 0.65
	10	<ul><li>10.7 The jumper on the PCB should conform to the product characteristic chart.</li><li>10.8 If solder gets on bezel tab pads, LED pad, zebra pad or</li></ul>	0.65
	1	screw hold pad, make sure it is smoothed down.  10.9 The Scraping testing standard for Copper Coating of PCB	2.5
Q		X X * Y<=2mm2	2.5
		11.1 No un-melted solder paste may be present on the PCB.  11.2 No cold solder joints, missing solder connections, oxidation	2.5 2.5
11	Soldering	or icicle.	0
		<ul><li>11.3 No residue or solder balls on PCB.</li><li>11.4 No short circuits in components on PCB.</li></ul>	2.5 0.65
<u> </u>		The state of the s	0.00



NO	Item	Criterion	AQL
		12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.  12.2 No cracks on interface pin (OLB) of TCP.	2.5
		12.3 No contamination, solder residue or solder balls on product.	0.65
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface	2.5
	General appearance	pin must be present or look as if it cause the interface pin to	
12		sever.	2.5
12		12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.	0.5
		12.7 Sealant on top of the ITO circuit has not hardened.	2.5 0.65
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on	
		packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to product specification sheet.	
		12.12 Visual defect outside of VA is not considered to be rejection.	



### 11.Precautions in use of LCD Modules

- (1)Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6)Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) Raystar have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9)Raystar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)



### 12. Material List of Components for RoHs

1. RAYSTAR Display Co., Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

#### 2.Process for RoHS requirement:

- (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
- (2) Heat-resistance temp. :

Reflow: 250°C,30 seconds Max.;

Connector soldering wave or hand soldering : 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°€;

Recommended customer's soldering temp. of connector: 280°C, 3 seconds.



## 13. Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.



Page: 1

		i age. i			
	LCM Sample	e Estimate Feedback Sheet			
Module Number :					
1 · Panel Specification :					
1. Panel Type:	□ Pass	□ NG ,			
2. View Direction:	□ Pass	□ NG ,			
3. Numbers of Dots:	□ Pass	□ NG ,			
4. View Area:	□ Pass	□ NG ,			
5. Active Area:	□ Pass	□ NG ,			
6.Operating Temperature:	□ Pass	□ NG ,			
7.Storage Temperature:	□ Pass	□ NG ,			
8.Others:	1				
2 · Mechanical Specification :					
1. PCB Size :	□ Pass	□ NG ,			
2.Frame Size :	□ Pass	□ NG ,			
3.Materal of Frame:	□ Pass	□ NG ,			
4.Connector Position:	□ Pass	□ NG ,			
5.Fix Hole Position:	□ Pass	□ NG ,			
6.Backlight Position:	□ Pass	□ NG ,			
7. Thickness of PCB:	□ Pass	□ NG ,			
8. Height of Frame to PCB:	□ Pass	□ NG ,			
9.Height of Module:	□ Pass	□ NG ,			
10.Others:	□ Pass	□ NG ,			
3 · Relative Hole Size :					
1.Pitch of Connector:	□ Pass	□ NG ,			
2.Hole size of Connector:	□ Pass	□ NG ,			
3.Mounting Hole size:	□ Pass	□ NG ,			
4.Mounting Hole Type:	□ Pass	□ NG ,			
5.Others:	□ Pass	□ NG ,			
4 · Backlight Specification :					
1.B/L Type:	□ Pass	□ NG ,			
2.B/L Color:	□ Pass	□ NG ,			
3.B/L Driving Voltage (Referen	ce for LED Ty	pe) :   Pass   NG ,			
4.B/L Driving Current:	□ Pass	□ NG ,			
5.Brightness of B/L:	□ Pass	□ NG ,			
6.B/L Solder Method:	□ Pass	□ NG ,			
7.Others:	□ Pass	□ NG,			

>> Go to page 2 <<



Page: 2

Module Number :					
5 · Electronic Characteristics of Module :					
1.Input Voltage:	□ Pass	□ NG ,			
2.Supply Current:	□ Pass	□ NG ,			
3.Driving Voltage for LCD:	□ Pass	□ NG ,			
4.Contrast for LCD:	□ Pass	□ NG ,			
5.B/L Driving Method:	□ Pass	□ NG ,			
6.Negative Voltage Output:	□ Pass	□ NG ,			
7.Interface Function:	□ Pass	□ NG ,			
8.LCD Uniformity:	□ Pass	□ NG ,			
9.ESD test:	□ Pass	□ NG ,			
10.Others:	□ Pass	□ NG ,			
6 · Summary :					
Sales signature :					
Customer Signature :					